

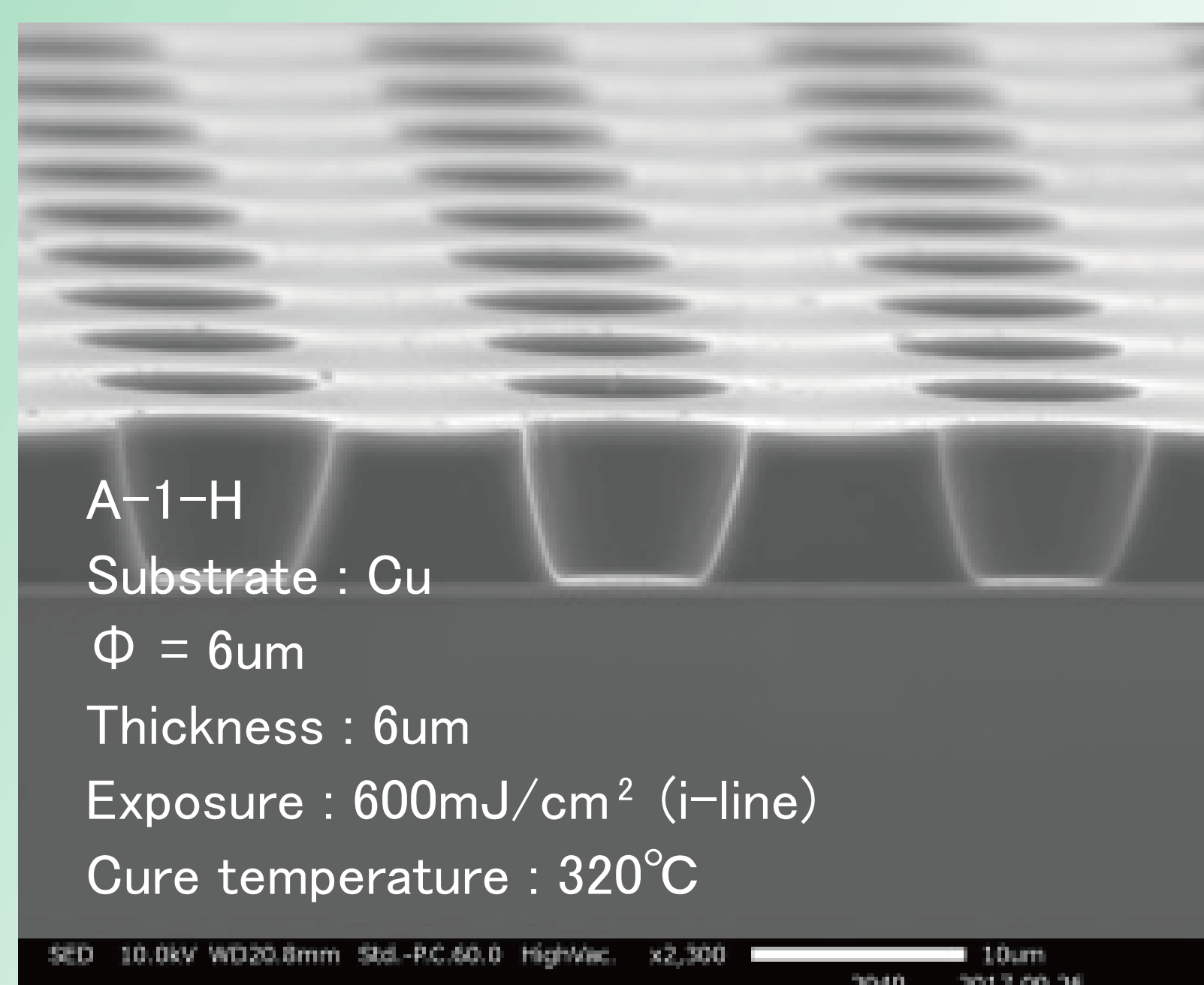


Photosensitive Dielectric material for Semiconductor "A-1 series"

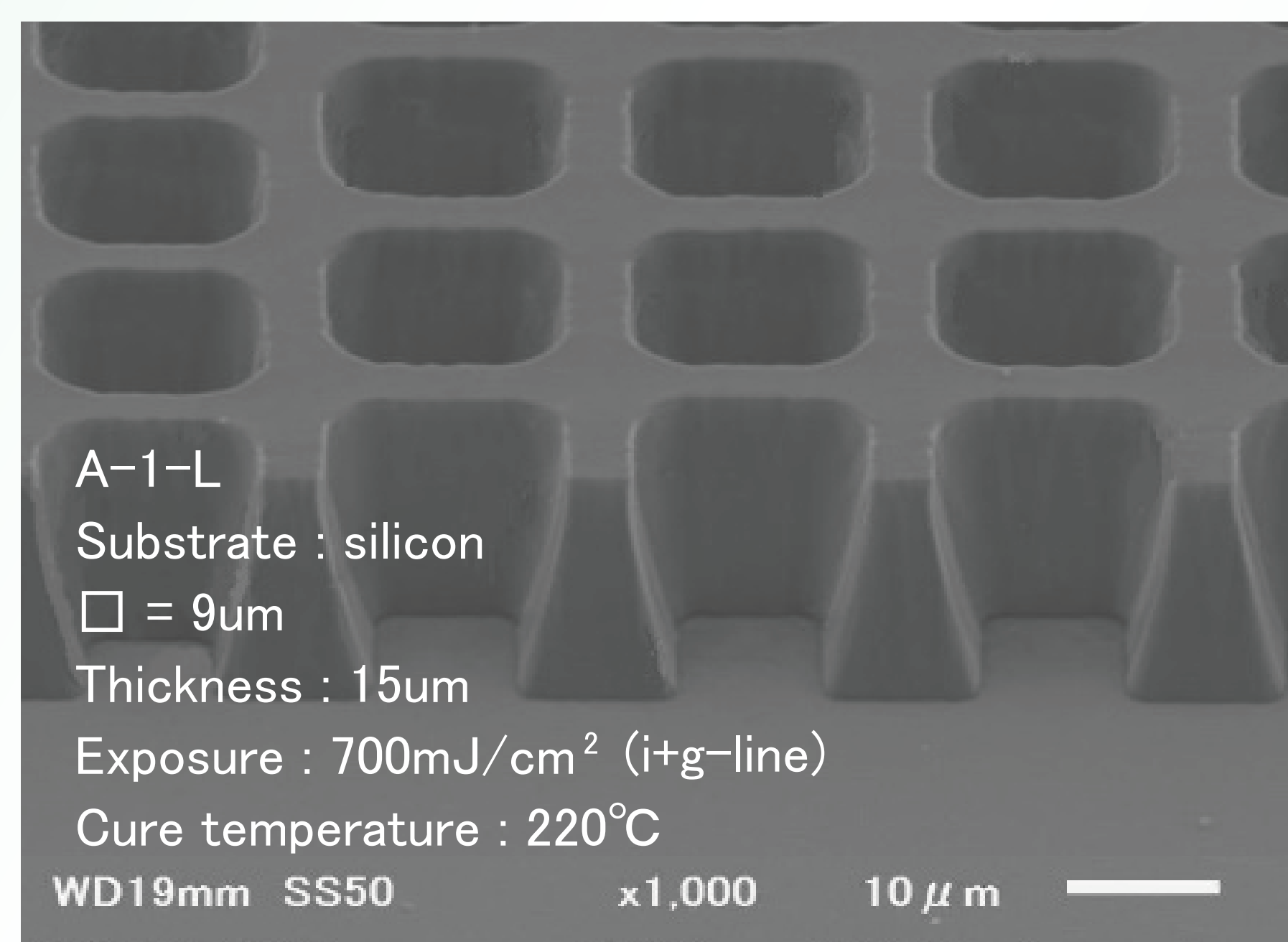
-Suitable for Buffer coat and re-distribution layer-

特徴 Features

- ✓ **High resolution**
A-1 series can form fine pattern
- ✓ **Good thermomechanical**
A-1 series show high heat-resistance and high mechanical properties
- ✓ **Wide thickness margin**
A-1 series applicable for thick film



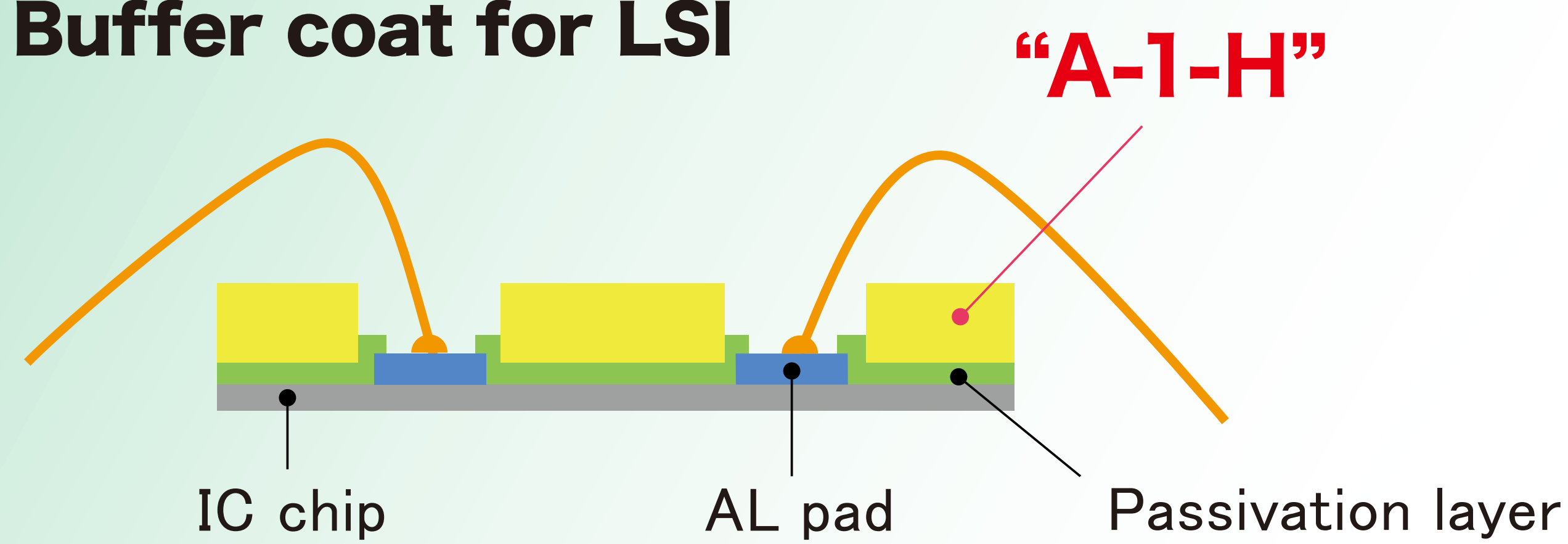
Low Dk/Df **A-1-H**



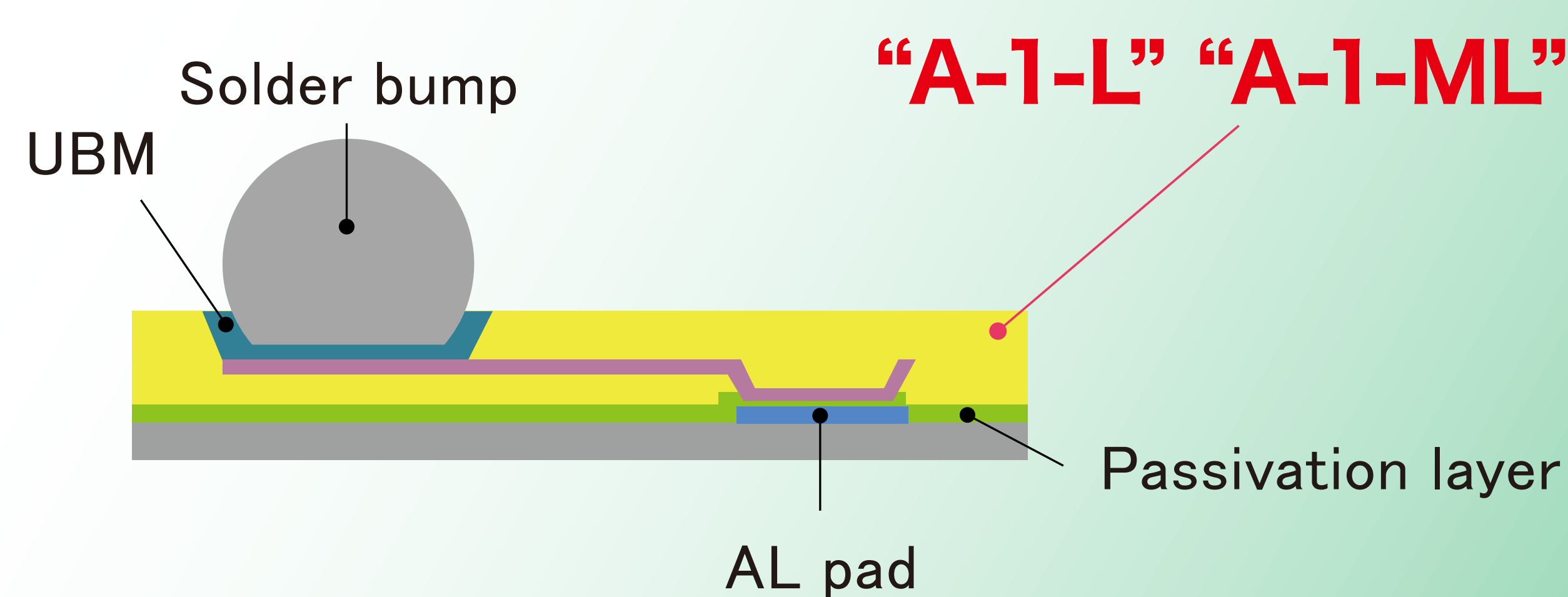
Low curing temp. 220°C **A-1-L**

用途例 Application

Buffer coat for LSI



Re-distribution Layer for WLP



特性 Film Properties

Item	unit	A-1-H	A-1-L	A-1-ML
Curing temp.	°C	320	220	240
Tg (TMA)	°C	315	322	245
CTE	ppm/°C	51	50	65
5% weight loss temp	°C	495	310	372
Tensile strength	MPa	110	114	109
Young's modulus	GPa	2.5	2.9	2.7
Breaking elongation	%	53	27	53
Dk (10GHz)		2.79	3.2	2.93
Df (10GHz)		0.005	0.021	0.009